# PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2873140

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|---|---|
| **SUBMISSION TYPE:** | NEW ASSIGNMENT |
| **NATURE OF CONVEYANCE:** | ASSIGNMENT |

## CONVEYING PARTY DATA

| Name | Execution Date |
|---|---|
| WEIHAI BU | 05/15/2014 |
| JIN KANG | 05/15/2014 |
| YONG CHEN | 05/15/2014 |
| XINPENG WANG | 05/13/2014 |

## RECEIVING PARTY DATA

| | |
|---|---|
| **Name:** | SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION |
| **Street Address:** | 18 ZHANGJIANG ROAD, PUDONG NEW AREA |
| **City:** | SHANGHAI |
| **State/Country:** | CHINA |
| **Postal Code:** | 201203 |

## PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---|---|
| **Application Number:** | 14288627 |

## CORRESPONDENCE DATA

**Fax Number:**

***Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.***

| | |
|---|---|
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|---|---|
| **ATTORNEY DOCKET NUMBER:** | 00158.0193.00US |
| **NAME OF SUBMITTER:** | MENG LIU |
| **SIGNATURE:** | /MENG LIU/ |
| **DATE SIGNED:** | 05/28/2014 |

**Total Attachments: 3**
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# ASSIGNMENT

WHEREAS I/We, the below named inventor(s) (hereinafter referred to as Assignor(s)) have made an invention entitled:

**TRANSISTOR AND METHOD FOR FORMING THE SAME**

for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on ________ (Application No. ____________); and

WHEREAS, Semiconductor Manufacturing International (Shanghai) Corporation, a corporation of P. R. China whose post office address is 18 Zhangjiang Road, Pudong New Area, Shanghai, China 201203 (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention, provisional Application No. _______, filed ___________ (if any), and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of the above provisional application (if any), as well as all rights to claim priority on the basis of this application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No._____, filed _______________) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands.

Inventor 1:

Name: WEIHAI BU
Address: 18 Zhangjiang Road, Pudong New Area
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Signature: Weihai Bu
Date: 2014-5-15

Inventor 2:

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Signature: Jin Kang
Date: 2014-5-15

Inventor 3:

Name: YONG CHEN
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Date: 2014.5.15

Inventor 4:

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Signature: Xinpeng. Wang

Date: 2014-5-13